Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
7280-US - Aruba 7280 (US) Controller
7280-RW- Aruba 7280 (RW) Controller
7280-JP - Aruba 7280 (JP) Controller
7280-IL - Aruba 7280 (IL) Controller
7280-EG - Aruba 7280 (EG) Controller

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries LITHIUM 3V 195mAh BR2032-BA LT RAYOVAC	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries BR2032	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords	RW Sku ---1 USB cable US Sku-----1 USB cable, 1 power cord	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Phillips Screw Driver	P1 ,P2
Flat Screw Driver	Any

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Use a P1 Phillips screw driver to remove all 16 screws on chassis. (see Figure 1).
2. After remove the top cover, extract the PSU and power supply. (see Figure 2) .
3. Use a P1 ,P2 Phillips screw driver to remove all 28 screws on internal (see Figure 3).
4. Remove the plastic bezel and Fan*5pcs (see Figure 3).
5. Remove the FIPS bracket and baffle right/ baffle left (see Figure 4).
6. Remove cable *2. (see Figure 4).
7. Remove all module on main board and LED/FAN board, total 11pcs (see Figure 5).
8. Use Flat screw driver and P1 Phillips screw driver to remove all heatsink on main board. (see Figure 6).
9. Use Flat screw driver and P1 Phillips screw driver to remove the battery on main board. (see Figure 7).

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Figure 1 : Remove all screw on chassis, total 16pcs.

Remove all screw on chassis,total 16pcs.

Figure 2 : Extract the PSU and power supply.

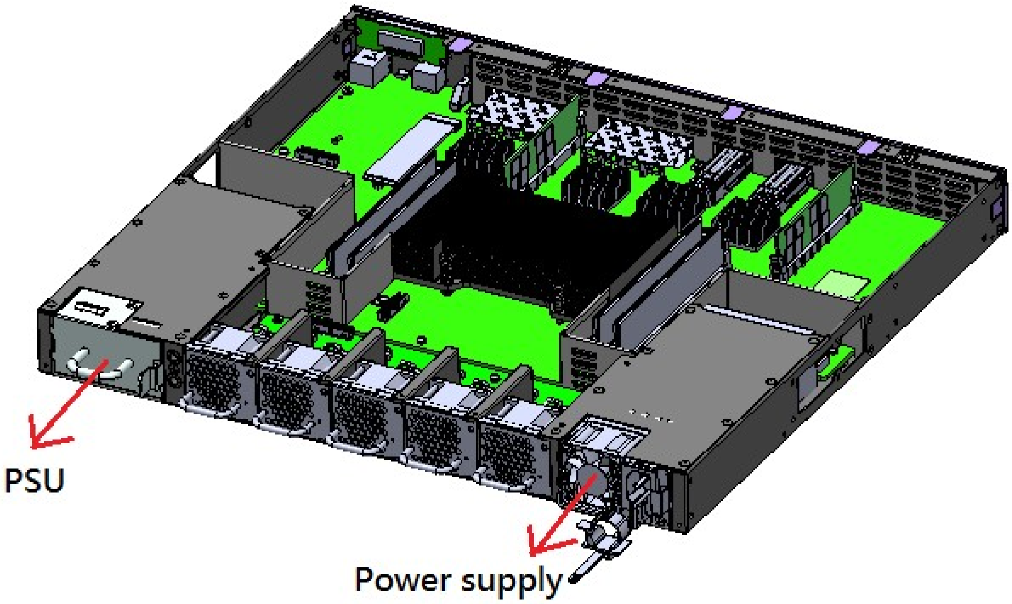

Figure 3 : Remove all screw on internal, total 28pcs.

Remove Bezel and FAN*5pcs.

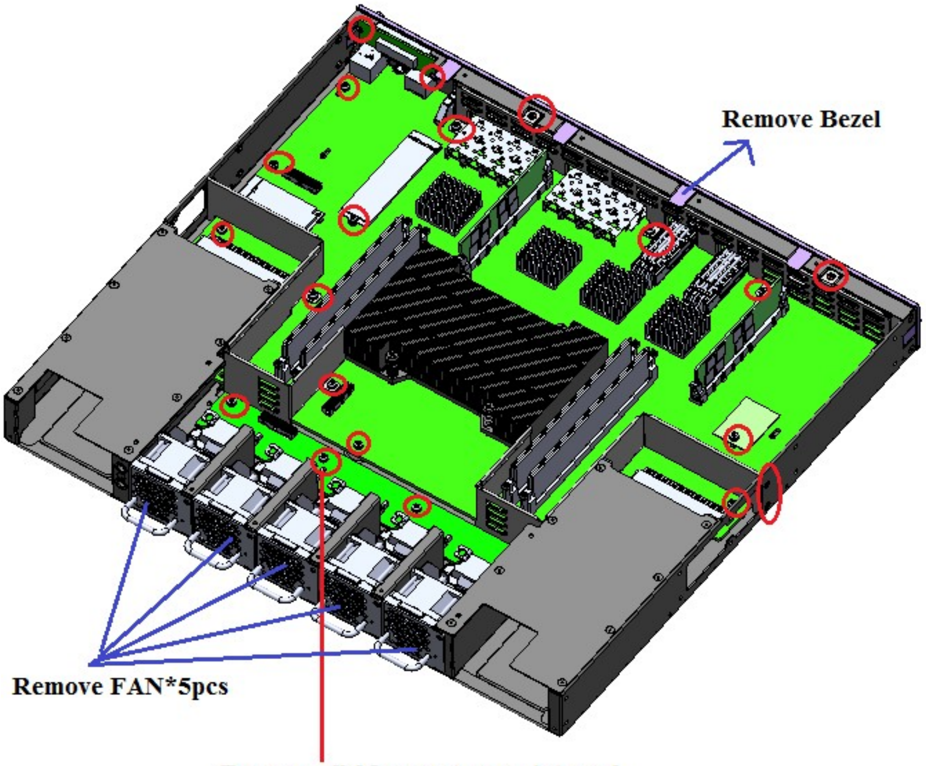

Figure 4 : Remove the FIPS bracket and baffle right /baffle left.

Remove Cable*2.

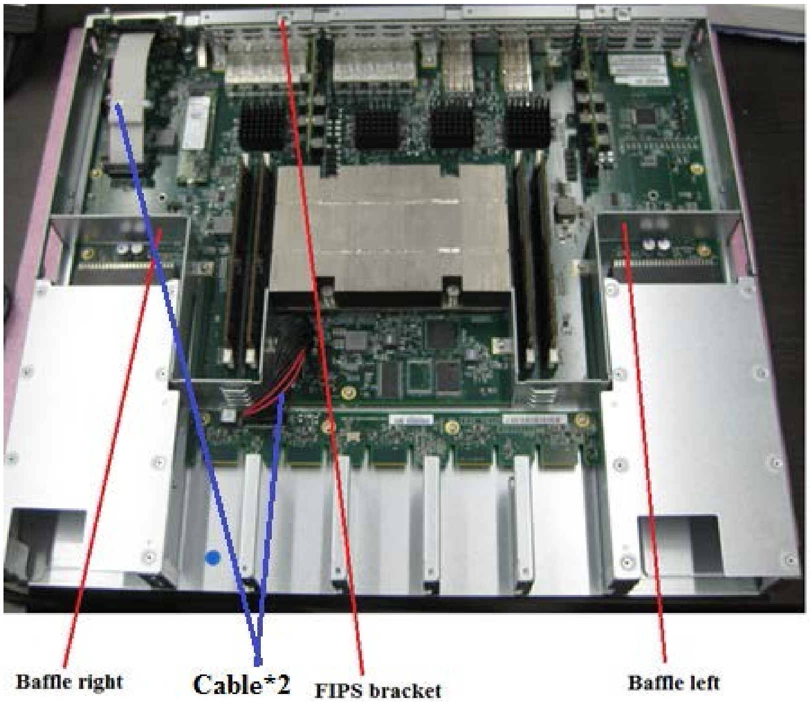

Figure 5 : Remove all module on main board and LED / FAN Module ,total 11pcs.

Remove base.

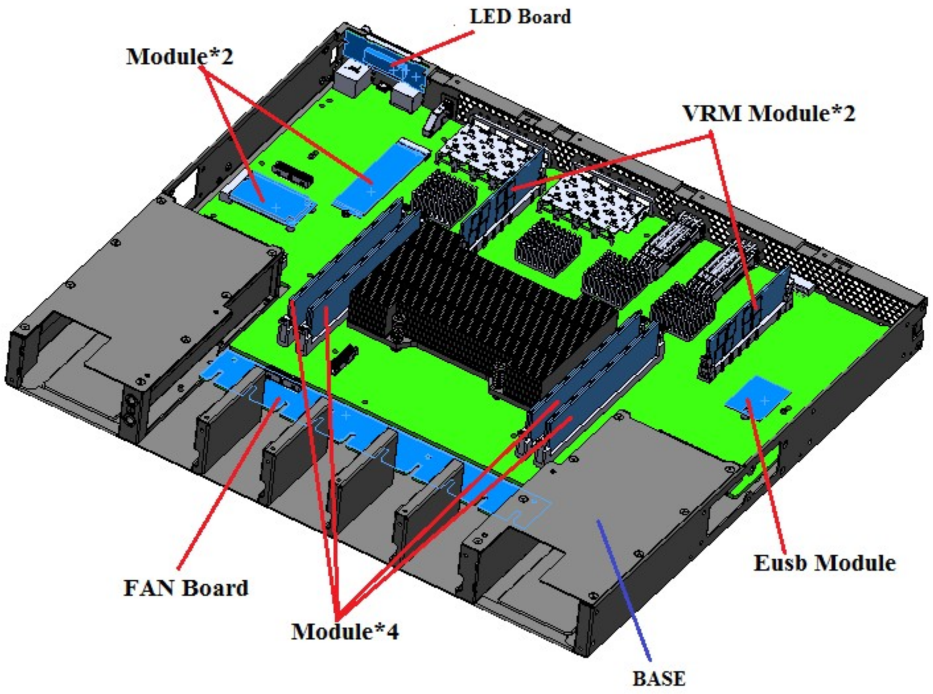

Figure 6: Remove all heatsink on main board, total 5pcs.

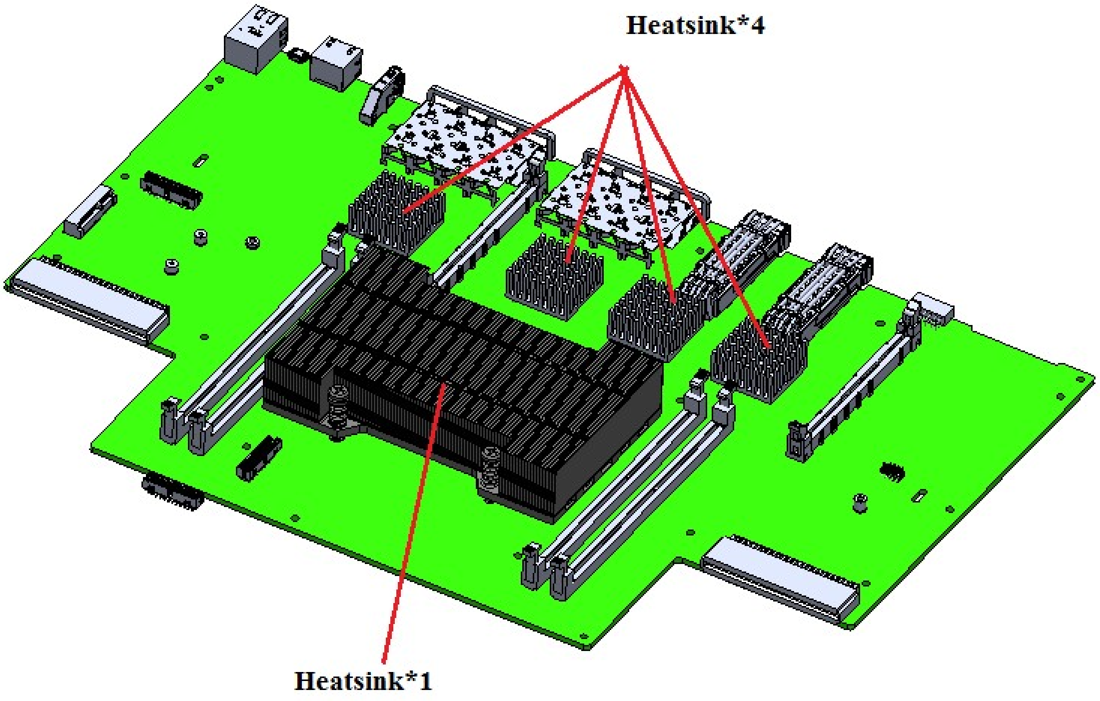

Figure 7: Battery location